

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-026829

(43)Date of publication of application : 25.01.2000

(51)Int.Cl. C09J163/00
C08G 59/40
C09J 9/02

(21)Application number : 10-193821

(71)Applicant : THREE BOND CO LTD

(22)Date of filing : 09.07.1998

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(54) THERMOSETTING ELECTROCONDUCTIVE ADHESIVE

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a thermosetting electroconductive adhesive improved in storage stability, which adhesive contains a product prepared by subjecting to a specified pretreatment a curing agent prepared by pretreating with an isocyanate the reaction product of an imidazole derivative with an epoxy compound.

SOLUTION: There is provided a thermosetting electroconductive adhesive comprising a curing agent prepared by pretreating with an isocyanate the reaction product of an imidazole derivative with an epoxy compound, an epoxy composition curable with the curing agent, and an electroconductive material, wherein the curing agent is further treated with an isocyanate compound and a polyol compound in an epoxy resin which does not dissolve or swell the curing agent. In an embodiment, the pretreatment with the isocyanate compound and the polyol compound is carried out by using 100 pts.wt. curing agent, 0.01-20 pts.wt. isocyanate compound, and 0.01-20 pts.wt. polyol compound.

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isocyanato compound and a polyol compound in an epoxy resin not dissolving or swelling the curative.

USE - The thermosetting electroconductive adhesives are for adhering counteracting wiring patterns by thermal contact bonding on electronic parts assembly.

ADVANTAGE - The thermosetting electroconductive adhesives have much improved storage stability, excellent solvent resistance and thermal and physical stability without foam mixing and fall in glass transition temperature even with use of a polyol compound.

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Title Terms: THERMOSETTING; ELECTROCONDUCTING; ADHESIVE; IMPROVE; STORAGE; STABILISED; COMPRISE; CURE; OBTAIN; TREAT; REACT; PRODUCT; IMIDAZOLE; DERIVATIVE; EPOXY; COMPOUND; ISOCYANATE

Derwent Class: A21; A25; A81; G03; L03

International Patent Class (Main): C09J-009/02; C09J-163/00

International Patent Class (Additional): C08G-059/40; C09J-175/00

File Segment: CPI

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DT04 Rec'd PCT/PTO 13 OCT 2004

File 351:Derwent WPI 1963-2004/UD,UM &UP=200463

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DIALOG(R)File 351:Derwent WPI
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WPI Acc No: 2000-177215/200016

XRAM Acc No: C00-055606

Thermosetting electroconductive adhesives with improved storage stability
- comprising a curative obtained by treating a reaction product of an imidazole derivative and an epoxy compound with an isocyanate

Patent Assignee: TOKYO THREE BOND CO LTD (TOKT)

Number of Countries: 001 Number of Patents: 002

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 2000026829	A	20000125	JP 98193821	A	19980709	200016 B
JP 3562323	B2	20040908	JP 98193821	A	19980709	200459

Priority Applications (No Type Date): JP 98193821 A 19980709

Patent Details:

Patent No	Kind	Lan Pg	Main IPC	Filing Notes
JP 2000026829	A	6	C09J-163/00	
JP 3562323	B2	10	C09J-009/02	Previous Publ. patent JP 2000026829

Abstract (Basic): JP 2000026829 A

NOVELTY - A thermosetting electroconductive adhesive comprises a curative obtained by treating a reaction product of an imidazole derivative and an epoxy compound with an isocyanate, an epoxy composition to be cured with the curative and an electroconductive material.

DETAILED DESCRIPTION - The curative is further treated with an isocyanato compound and a polyol compound in an epoxy resin not dissolving or swelling the curative.

USE - The thermosetting electroconductive adhesives are for adhering countering wiring patterns by thermal contact bonding on electronic parts assembly.

ADVANTAGE - The thermosetting electroconductive adhesives have much improved storage stability, excellent solvent resistance and thermal and physical stability without foam mixing and fall in glass transition temperature even with use of a polyol compound.

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